

ABSTRACT OF THE DISCLOSURE

~~(PROBLEM)~~ ~~To improve~~ The invention provides a method of manufacturing a semiconductor that improves the productivity and the yield of a product, and to grindgrinds a semiconductor substrate so that it has almost uniform thickness. The method can include forming a

~~(MEANS TO SOLVE THE PROBLEM)~~ A protrusion 40 ~~is formed~~ on a semiconductor substrate 10 having a first area 20 and a second area 30 surrounding the first area. The 20, the protrusion 40 protruding above first area-20. A support 60 is being disposed on a surface on which the protrusion 40 is formed, of the semiconductor substrate 10 so that a through hole 61 of the support 60 overlaps with the first area-20. The semiconductor substrate 10 is can be grinded from a surface opposite to the surface on which the protrusion 40 is formed.

~~(SELECTED FIGURE)~~ FIG. 5